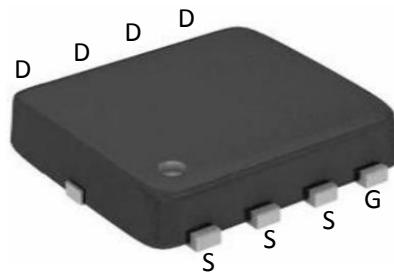


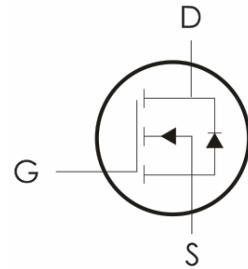
Description:

This N-Channel MOSFET uses advanced trench technology and design to provide excellent RDS(on) with low gate charge. It can be used in a wide variety of applications.



Features:

- 1) $V_{DS}=30V, I_D=60A, R_{DS(ON)}<6m\Omega @ V_{GS}=10V$
- 2) Improved dv/dt capability
- 3) Fast switching
- 4) 100% EAS Guaranteed
- 5) Green Device Available.



Absolute Maximum Ratings: ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current-Continuous ($TC=25^\circ C$)	60	A
	Continuous Drain Current- $TC=100^\circ C$	38	
I_{DM}	Drain Current – Pulsed ¹	240	A
E_{AS}	Single Pulse Avalanche Energy ²	88	mJ
P_D	Power Dissipation ($TC=25^\circ C$)	45	W
	Power Dissipation – Derate above $25^\circ C$	0.36	$W/^\circ C$
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ C$

Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance,Junction to Case	62	°C/W
$R_{\theta JA}$	Thermal Resistance,Junction to Ambient	2.8	

Package Marking and Ordering Information:

Part NO.	Marking	Package
TSD60N03D	TSD60N03D	DNF3*3

Electrical Characteristics: ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250 \mu A$	30	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{GS}=0V, V_{DS}=30V, T_j=25^\circ C$	---	---	1	μA
		$V_{GS}=0V, V_{DS}=24V, T_j=125^\circ C$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0A$	---	---	± 100	nA
On Characteristics						
$V_{GS(th)}$	GATE-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250 \mu A$	1.2	1.6	2.5	V
$R_{DS(ON)}$	Drain-Source On Resistance ³	$V_{GS}=10V, I_D=20A$	---	---	6	$m \Omega$
		$V_{GS}=4.5V, I_D=10A$	---	---	9	
G_{FS}	Forward Transconductance	$V_{DS}=10V, I_D=10A$	---	23	---	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, f=1MHz$	---	1210	1800	pF
C_{oss}	Output Capacitance		---	190	280	
C_{rss}	Reverse Transfer Capacitance		---	100	150	
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time ^{3,4}	$V_{DD}=15V, V_{GS}=10V, R_G=3.3\Omega, I_D=15A$	---	7.5	14	ns
t_r	Rise Time ^{3,4}		---	14.5	28	ns
$t_{d(off)}$	Turn-Off Delay Time ^{3,4}		---	32.5	67	ns

t_f	Fall Time ^{3,4}		---	9.6	18	ns
Q_g	Total Gate Charge ^{3,4}	$V_{DS}=15V, V_{GS}=4.5V, I_D=20A$	---	11.1	18	nC
Q_{gs}	Gate-Source Charge ^{3,4}		---	1.85	3.8	nC
Q_{gd}	Gate-Drain "Miller" Charge ^{3,4}		---	6.8	12	nC

Drain-Source Diode Characteristics

V_{SD}	Source-Drain Diode Forward Voltage ²	$V_{GS}=0V, I_S=1A, T_J=25^\circ C$	---	---	1	V
t_{rr}	Reverse Recovery Time	$V_{GS}=0V, I_S=1A, di/dt=100A/\mu s, T_J=25^\circ C$	---	---		nS
Q_{rr}	Reverse Recovery Charge		---	---		nC

Notes:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=42A, RG=25, \text{Starting } T_J=25^\circ C$.
3. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

Typical Characteristics: ($T_c=25^\circ C$ unless otherwise noted)

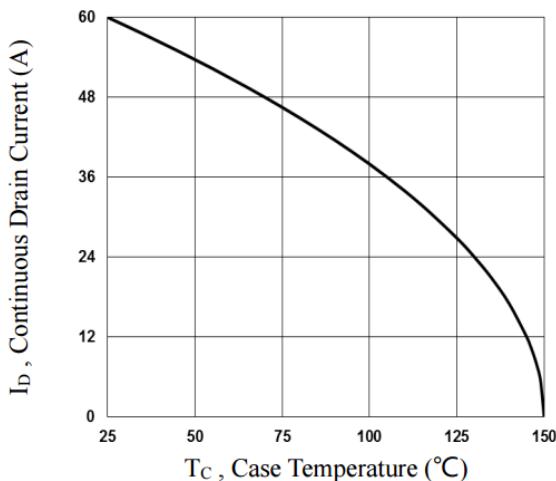


Fig.1 Continuous Drain Current vs. T_c

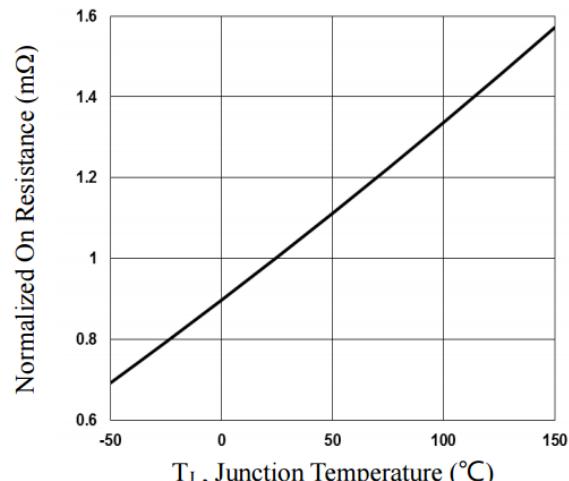


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

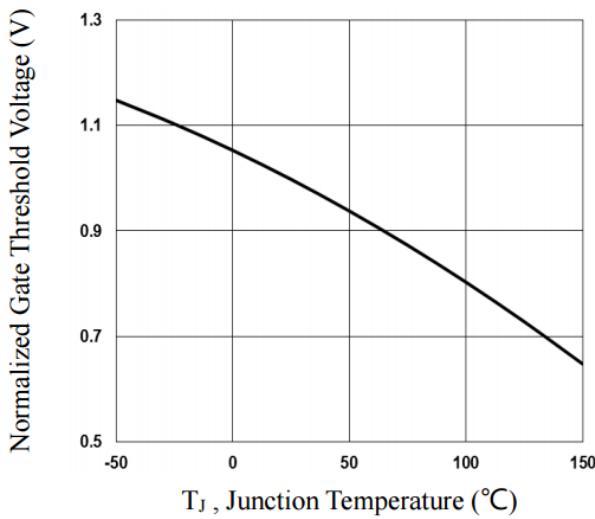


Fig.3 Normalized V_{th} vs. T_J

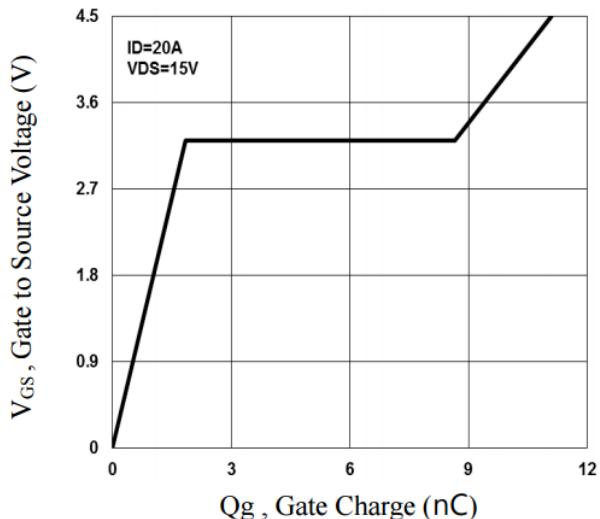


Fig.4 Gate Charge Waveform

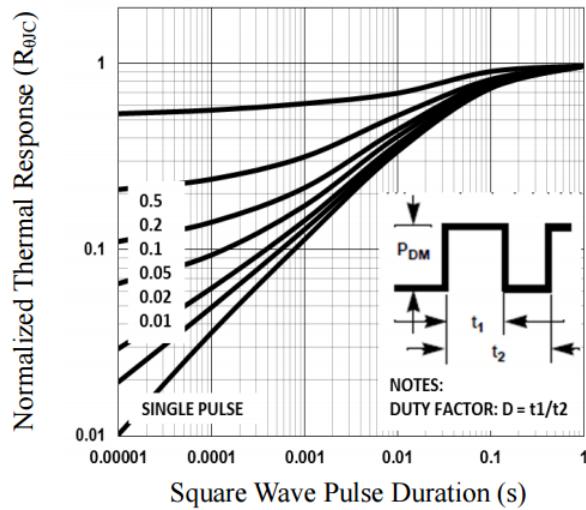


Fig.5 Normalized Transient Response

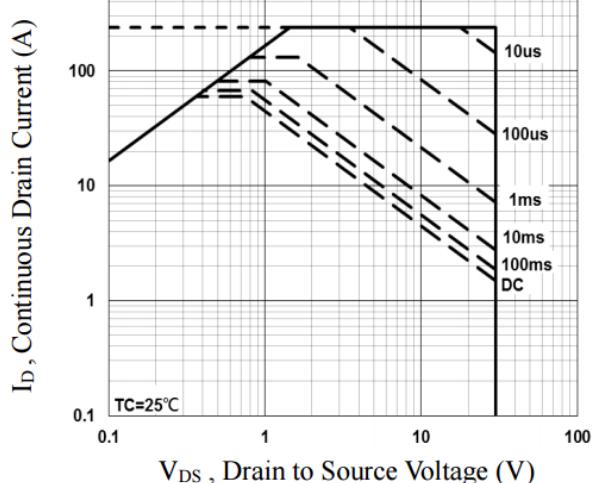


Fig.6 Maximum Safe Operation Area

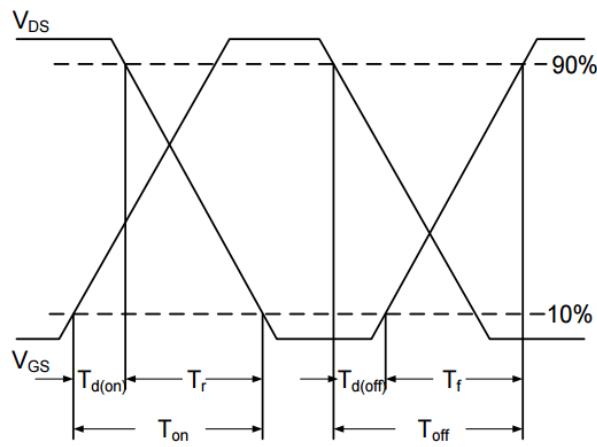


Fig.7 Switching Time Waveform

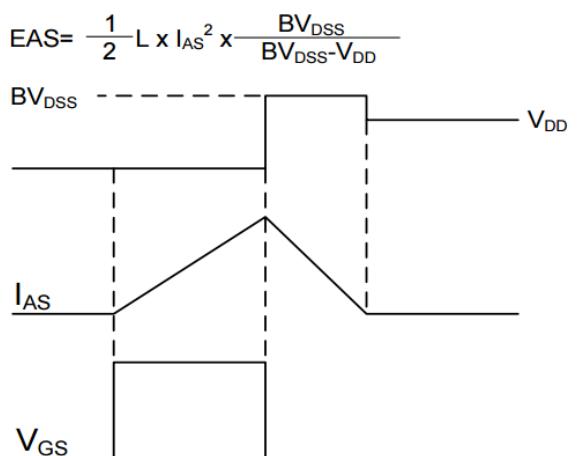


Fig.8 EAS Waveform